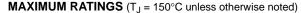
Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Pb-Free Package is Available
- Extremely Fast Switching Speed
- Low Forward Voltage



Rating	Symbol	Value	Unit
Reverse Voltage	V_R	70	V
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Operating Junction and Storage Temperature Range	T _{J,} T _{stg}	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

http://onsemi.com

70 VOLTS SCHOTTKY BARRIER DIODES





SOT-23 CASE 318 STYLE 8

MARKING DIAGRAM



BE Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS70LT1	SOT-23	3000 / Tape & Reel
BAS70LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Breakdown Voltage – (I _R = 10 μA)	V _{(BR)R}	70	-	V
Total Capacitance – (V _R = 0 V, f = 1.0 MHz)	C _T	-	2.0	pF
Reverse Leakage $(V_R = 50 \text{ V})$ $(V_R = 70 \text{ V})$	I _R	- -	0.1 10	μAdc
Forward Voltage – (I _F = 1.0 mAdc)	V _F	-	410	mVdc
Forward Voltage – (I _F = 10 mAdc)	V _F	-	750	mVdc
Forward Voltage – (I _F = 15 mAdc)	V _F	_	1.0	Vdc

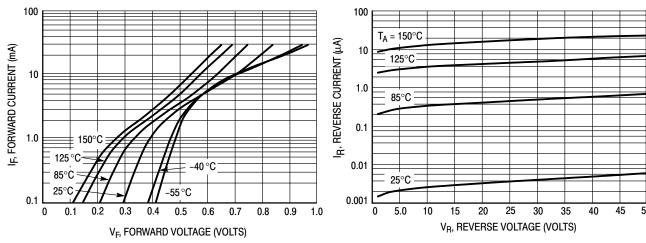


Figure 1. Typical Forward Voltage

Figure 2. Reverse Current versus Reverse Voltage

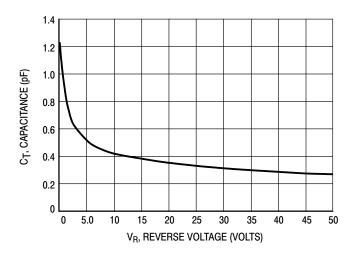
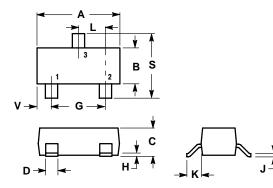


Figure 3. Typical Capacitance

PACKAGE DIMENSIONS

SOT-23 (TO-236)

CASE 318-08 **ISSUE AH**

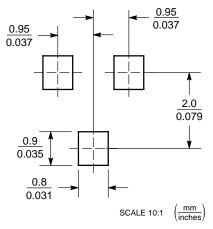


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318–03 AND -07 OBSOLETE, NEW STANDARD 318–08.
- STANDARD 318-08.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.1102	0.1197	2.80	3.04	
В	0.0472	0.0551	1.20	1.40	
С	0.0350	0.0440	0.89	1.11	
D	0.0150	0.0200	0.37	0.50	
G	0.0701	0.0807	1.78	2.04	
Н	0.0005	0.0040	0.013	0.100	
J	0.0034	0.0070	0.085	0.177	
K	0.0140	0.0285	0.35	0.69	
L	0.0350	0.0401	0.89	1.02	
S	0.0830	0.1039	2.10	2.64	
٧	0.0177	0.0236	0.45	0.60	

- STYLE 8:
 PIN 1. ANODE
 2. NO CONNECTION
 3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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